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L1 1 JP06184409/PN

L1 ANSWER 1 OF 1 WPIDS (C) 2002 THOMSON DERWENT

AN 1994-252985 [31] WPIDS

DNN N1994-199543 DNC C1994-115596

TI Curable electroconductive compsn. giving prod. which does not crack in curing - comprises epoxy resin, hardener and dendritic metal powder.

DC A21 A85 G02 L03 V04 X12

PA (TOKU) TOKUYAMA SODA KK

CYC 1

PI JP 06184409 A 19940705 (199431)\* 10p <--

JP 2742190 B2 19980422 (199821) 10p

ADT JP 06184409 A JP 1992-339208 19921218; JP 2742190 B2 JP 1992-339208 19921218

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AB JP 06184409 A UPAB: 19940921

Compsn. comprises (A) epoxy resin, (B) hardener and (C) dendritic metal powder which is contained in 300-2,000, pref. 400-700 pts.wt. power 100 pts.wt. of (A)+(B). (C) has a vol. average particle dia. of 10 to 15 microns, contains less than 0.05 vol.% of particles having a dia. of larger than 40 microns and has a standard deviation (log sigma) of lower than 0.26 as defined by logarithmic distribution function.

(A) comprises (a) bisphenol A glycidyl ether with an epoxy equiv. of lower than 200 g/equiv. and (b) at least one monoglycidyl cpd. selected from among 11-13C straight chain alkyl monoglycidyl ether and 9-11C straight chain alkyl monoglycidyl ester, with (b) contained in 20-60 wt.% of (a).

(B) is used in 0.3-2.0 equiv. per 1 equiv. of epoxy gp. (C) are e.g. Cu, Ag, and Fe powders.

ADVANTAGE - Curable electroconductive compsn. forms cured prod. which does not crack in curing even when it is thick and has consistently high electroconductivity over a long period. For filling in through-hole of circuit board.

Dwg.13

PI JP 06184409 A 19940705 (199431)\* 10p C08L063-00 <--

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